## **DESCRIPTION**

The AM10P06 is available in TO-252 Package

BVDSS	RDSON	ID
-60V	100mΩ	-10A

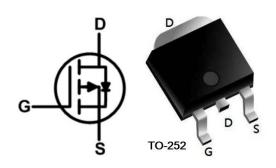
# **FEATURE**

- Advanced high cell density Trench Technology
- $R_{DS(ON)typ.}$ =100m $\Omega$  @  $V_{GS}$ =-10V
- Excellent dv/dt effect decline
- Super Low Gate Charge

## **ORDERING INFORMATION**

Package Type	Part Number		
TO-252	D	AM10P06DR	
SPQ: 2,500pcs/Reel	D	AM10P06DVR	
Note	V: Halogen free Package		
Note	R: Tape & Reel		
AiT provides all RoHS products			

## PIN DESCRIPTION



Pin#	Symbol	Function
1	G	Gate
2	D	Drain
3	S	Source

#### **ABSOLUTE MAXIMUM RATINGS**

T<sub>A</sub>= 25°C, unless otherwise specified.

Parameter		Symbol	Value	Unit		
Drain-Source Voltage		V <sub>DS</sub>	-60	V		
Gate-Source Voltage		V <sub>G</sub> s	±20	V		
	I <sub>D</sub> @T <sub>A</sub> = 25°C		-12			
Continuous Drain Current,	I <sub>D</sub> @T <sub>C</sub> = 100°C	I <sub>D</sub>	-7.8	^		
V <sub>GS</sub> @ -10V <sup>1</sup>	I <sub>D</sub> @T <sub>A</sub> = 25°C		-3.5	A		
	I <sub>D</sub> @T <sub>A</sub> =70°C		-2.8			
Pulsed Drain Current (2)		Ірм	-25	Α		
Single Pulsed Avalanche Energy (3)		E <sub>AS</sub>	20	mJ		
Avalanche Current		las	-20	Α		
Total Power Dissipation (4)	rer Dissipation (4) T <sub>C</sub> =25°C		25	W		
Total Power Dissipation (4) T <sub>A</sub> =25°C		P <sub>D</sub>	2	W		
Junction Temperature		TJ	150	°C		
Storage Temperature Range		torage Temperature Range		T <sub>STG</sub>	-55 to 150	°C
THERMAL DATA						
Thermal Resistance Junction-ambient (1)		R <sub>θ</sub> JA	62	°C/W		
Thermal Resistance Junction-Case (1)		Rejc	5	°C/W		

Stresses above may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these or any other conditions beyond those indicated in the Electrical Characteristics are not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

- (1) The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper.
- (2) The data tested by pulsed , pulse width  $\leq$  300us , duty cycle  $\leq$  2%
- (3) The EAS data shows Max. rating. The test condition is  $V_{DD}$ =-25V,  $V_{GS}$ =-10V, L=0.1mH,  $I_{AS}$ =-15A
- (4) The power dissipation is limited by 150°C junction temperature

# **ELECTRICAL CHARACTERISTICS**

T<sub>A</sub> = 25°C, unless otherwise specified.

A = 25°C, unless otherwise specified.				11.11			
Parameter	Symbol	Conditions	Min	Тур.	Max.	Unit	
Static Characteristics							
Drain-Source Breakdown Voltage	$BV_{DSS}$	$V_{GS} = 0V$ , $I_D = -250\mu A$	-60	-	-	V	
BV <sub>DSS</sub> Temperature Coefficient	△BV <sub>DSS</sub> /△T <sub>J</sub>	Reference to 25°C , I <sub>D</sub> =-1mA	-	-0.049	-	V/°C	
Drain Source Leakage Current		V <sub>DS</sub> =-48V, V <sub>GS</sub> =0V	-	-	1	μА	
Drain-Source Leakage Current	I <sub>DSS</sub>	V <sub>DS</sub> =-48V, V <sub>GS</sub> =0V, T <sub>J</sub> =150°C	-	-	5		
Gate-Source Leakage Current	I <sub>GSS</sub>	$V_{DS} = 0V, V_{GS} = \pm 20V$	-	-	±100	nA	
Gate-Threshold Voltage	$V_{GS(th)}$	V <sub>GS</sub> =V <sub>DS</sub> , I <sub>D</sub> =-250uA	-1.0	-	-2.5	V	
V <sub>GS (th)</sub> Temperature Coefficient	${^{\triangle}V_{GS(th)}}$	VGS-VDS, ID250UA	-	5.42	-	mV/°C	
Static Drain-Source	D	$V_{GS} = -10V, I_{D} = -8A$	-	100	140	mΩ	
On-Resistance (2)	R <sub>DS(ON)</sub>	$V_{GS} = -4.5V$ , $I_{D} = -6A$	-	115	190		
Forward Transconductance	<b>g</b> fs	V <sub>DS</sub> =-5V, I <sub>D</sub> =-5A	-	5.8	-	S	
Dynamic Characteristics							
Input Capacitance	C <sub>iss</sub>	\\ - 45\\ \\ -0\\	-	715	-	pF	
Output Capacitance	Coss	V <sub>DS</sub> = -15V, V <sub>GS</sub> =0V, f =1MHz	-	51	-		
Reverse Transfer Capacitance	$C_{rss}$	1 - 11VII 12	-	34	-		
Switching Characteristics							
Total Gate Charge (-4.5V)	Qg		-	5.85	-	nC	
Gate-Source Charge	$Q_{gs}$	$V_{DS} = -20V, V_{GS} = -4.5V,$	-	2.9	-		
Gate-Drain Charge	$Q_{gd}$	I <sub>D</sub> = -5A	-	1.8	-		
Turn-on Delay Time	t <sub>d (ON)</sub>	\\ - 40\\ I - 50	-	10	-	nS	
Turn-on Rise Time	$t_r$	$V_{DD}$ =-12V, $I_{D}$ =-5A, $R_{G}$ =3.3 $\Omega$	-	17	-		
Turn-Off Delay Time	t <sub>d (OFF)</sub>	V <sub>GS</sub> =-10V	-	22	-		
Turn-Off Fall Time	$t_{f}$	VGS10V	-	21	-		
Diode Characteristics							
Continuous Source Current (1)(5)	Is	V V 0V 5 0 1	-	-	-9.5	Α	
Pulsed Source Current (2)(5)	I <sub>SM</sub>	V <sub>G</sub> =V <sub>D</sub> =0V, Force Current	-	_	-24	Α	
Diode Forward Voltage (2)	V <sub>SD</sub>	V <sub>GS</sub> =0V , I <sub>S</sub> =-1A , T <sub>J</sub> =25°C	-	_	-1.2	V	
Reverse Recovery Time	t <sub>rr</sub>	I <sub>F</sub> =-8A , dI/dt=100A/μs ,	_	10.2	-	nS	
Reverse Recovery Charge	Qrr	T <sub>J</sub> =25°C	-	5.4	_	nC	

- (1) The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper.
- (2) The data tested by pulsed , pulse width  $\leq$  300us , duty cycle  $\leq$  2%
- (5) The data is theoretically the same as ID and IDM, in real applications, should be limited by total power dissipation.



#### TYPICAL PERFORMANCE CHARACTERISTICS

Fig 1. Typical Output Characteristics

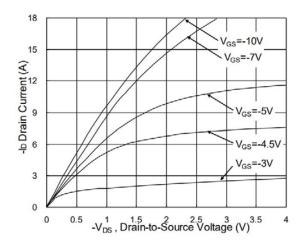


Fig 3. Forward Characteristics of Reverse

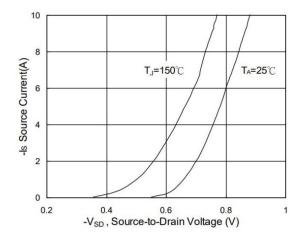


Fig 5. Normalized V<sub>GS (th)</sub> vs T<sub>J</sub>

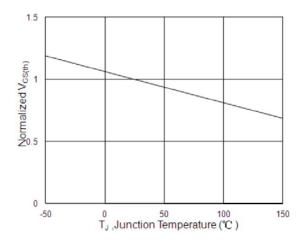


Fig 2. On-Resistance vs G-S Voltage

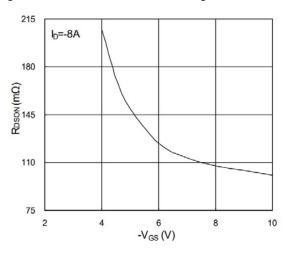


Fig 4. Gate-Charge Characteristics

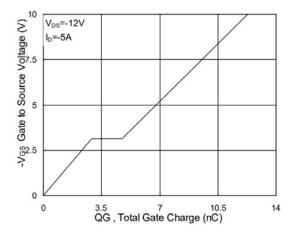


Fig 6. Normalized R<sub>DSON</sub> vs T<sub>J</sub>

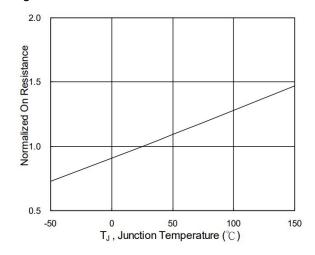


Fig 7. Capacitance

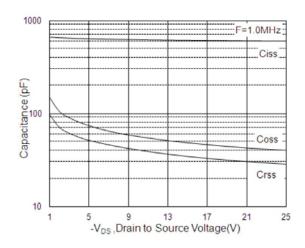


Fig 8. Safe Operating Area

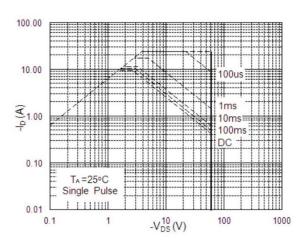


Fig 9. Normalized Maximum Transient Thermal Impedance

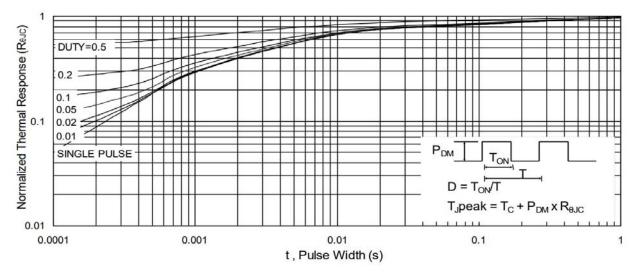


Fig 10. Switching Time Waveform

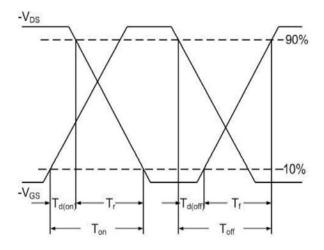
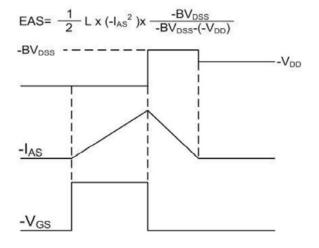
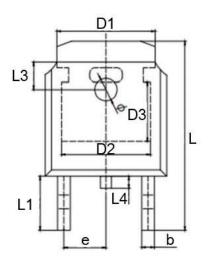


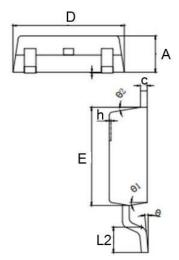
Fig 11. Unclamped Inductive Switching Waveform



# PACKAGE INFORMATION

Dimension in TO-252 (Unit: mm)





Symbol	Min.	Max.			
Α	2.200	2.400			
A1	0.000	0.127			
b	0.640	0.740			
С	0.460	0.580			
D	6.500	6.700			
D1	5.334REF				
D2	4.826REF				
D3	3.166REF				
E	6.000	6.200			
е	2.286TYP				
h	0.000	0.200			
L	9.900	10.30			
L1	2.888REF				
L2	1.400	1.700			
L3	1.600REF				
L4	0.600	1.000			
Ф	1.100	1.300			
θ	0° 8°				
θ1	9°				
θ2	9°				

AM10P06 MOSFET -60V, -10A P-CHANNEL

#### IMPORTANT NOTICE

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